Green Journals

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Journal Information

Journal Title	Electronic Device Failure Analysis
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Classification History

Year	A+	A	B	C
2026			✓	
2025			✓	
2024			✓	
2023			✓	
2021/2022			✓	
2020			✓	
2019			✓	
2018				

Classification: The table above shows all journal classifications recorded for each classification year in the Green Journals database. A journal may have more than one classification in the same year.

Recent Articles

Moisture and Microelectronic Devices
2026-8-1 Vol. 28 Issue 3 Pages 11-14
Authors: Philipp wh Schuessler
DOI: 10.31399/asm.edfa.2026-3.p011

Semiconductor Failure Analysis in the CHIPS Metrology Program
2026-8-1 Vol. 28 Issue 3 Pages 2-40
Authors: Bob Keller, Rebecca Routson
DOI: 10.31399/asm.edfa.2026-3.p002

Automated End-to-End AI Solution for Photon Emission Microscopy in Semiconductor Failure Analysis
2026-8-1 Vol. 28 Issue 3 Pages 18-23
Authors: Guofeng You, Silambarasan Karuppannan, Kan Sun et al.
DOI: 10.31399/asm.edfa.2026-3.p018

Leading the Charge in Building Today's Microelectronics Workforce
2026-8-1 Vol. 28 Issue 3 Pages 26-28
Authors: Errol Flynn
DOI: 10.31399/asm.edfa.2026-3.p026

Expanding the Application Range of Electron Beam Induced Resistance Change from Low- to High-Ohmic Failure
2026-8-1 Vol. 28 Issue 3 Pages 4-10
Authors: Oscar Recalde-Benitez, Andreas Rummel, Stephan Kleindiek
DOI: 10.31399/asm.edfa.2026-3.p004

From System Zap to Silicon Improvement: Advanced Fault Isolation of USB2 Electrostatic Discharge Failures

2026-5-1 Vol. 28 Issue 2 Pages 32-40
Authors: Omkar Rajesh Kachare
DOI: 10.31399/asm.edfa.2026-2.p032

Failure Analysis Outreach Council: Awareness, Education, Influence

2026-5-1 Vol. 28 Issue 2 Pages 2-40
Authors: Keith Serrels
DOI: 10.31399/asm.edfa.2026-2.p002

International Roadmap for Failure Analysis: Die-Level Roadmap Council

2026-5-1 Vol. 28 Issue 2 Pages 28-31
Authors: Kristofor Dickson, Venkat-Krishnan Ravikumar
DOI: 10.31399/asm.edfa.2026-2.p028

Electrical Fault Localization of High-Density 3D Interconnect Via Chains Through Innovative Sample Preparation

2026-5-1 Vol. 28 Issue 2 Pages 4-10
Authors: Kristof J.P. Jacobs
DOI: 10.31399/asm.edfa.2026-2.p004

Inspection and Metrology Challenges in Hybrid Bonding

2026-5-1 Vol. 28 Issue 2 Pages 12-24
Authors: Himanandhan Reddy Kottur, Pavanbabu Arjunamahanthi, Liton Kumar Biswas et al.
DOI: 10.31399/asm.edfa.2026-2.p012